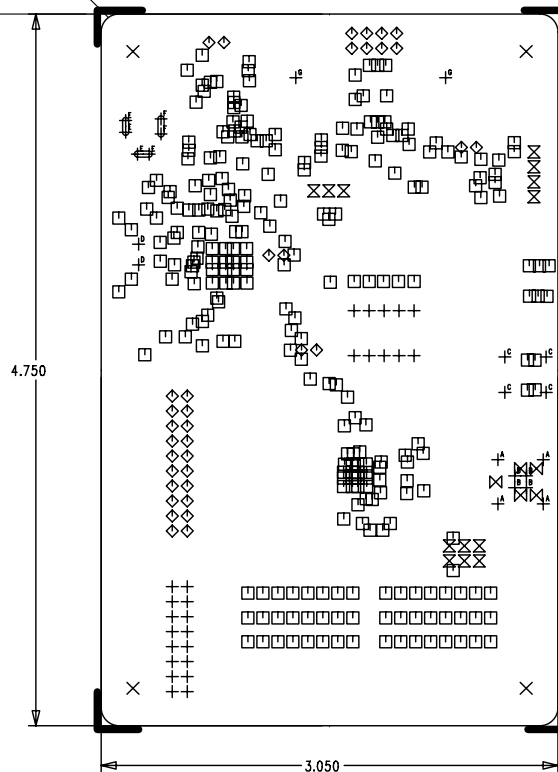


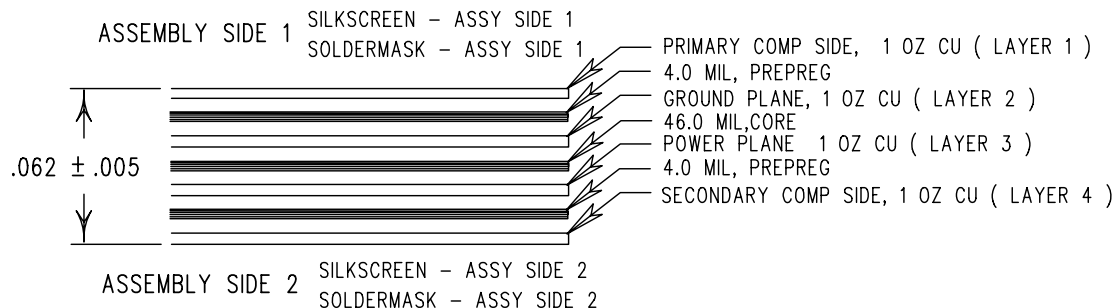
SIZE	QTY	SYM	PLATED	TOL
10	270	□	YES	+/-3.0
16	5	⊠	YES	+/-3.0
35	4	⊠ ^B	YES	+/-3.0
35.43	2	⊠ ^D	NO	+/-2.0
37	26	⊠	YES	+/-3.0
40 x 140	1	⊠ ^F	YES	+/-3.0
40	36	◇	YES	+/-3.0
40 x 118.11	2	⊠ ^E	YES	+/-3.0
43	13	⊠	YES	+/-3.0
62.99	4	⊠ ^C	YES	+/-3.0
65	4	⊠ ^A	YES	+/-3.0
156	4	⊠	YES	+/-3.0
265	2	⊠ ^G	YES	+/-3.0

UNIT:INCH

.12 R TYP
4 PLCS



DRILL DRAWING



NOTES: UNLESS OTHERWISE SPECIFIED

1. PRIMARY COMPONENT SIDE IS SHOWN.
2. ACCEPTABILITY SHALL BE BASED ON IPC-A-600, CLASS 2
3. MATERIAL: BASE MATERIAL IS FR-370HR, COLOR GREEN, 0.062 INCH NOM. THICKNESS. COPPER CLADDING SHALL BE 1 OZ.
4. PLATING: ALL HOLES AND CONDUCTIVE SURFACES SHALL BE PLATED WITH A MIN. OF .001 INCH COPPER. EXPOSED PADS / TRACES SHALL BE PLATED .000030 MIN GOLD OVER NICKEL, .000150 MIN. ENIG.
5. FABRICATION TOLERANCES:
END PRODUCT CONDUCTOR WIDTHS AND LAND DIAMETERS SHALL NOT VARY MORE THAN .002 INCH FROM THE 1:1 DIMENSIONS OF THE MASTER PATTERN. THE CONDUCTIVE PATTERN SHALL BE POSITIONED SO THAT THE LOCATION OF ANY LAND SHALL BE WITHIN .010 INCH DIAMETER TO THE TRUE POSITION OF THE HOLE IT CIRCUMSCRIBES THE MINIMUM ANNULAR RING SHALL BE .002 INCH. BOW AND TWIST SHALL NOT EXCEED .010 INCH PER INCH.
6. SOLDERMASK BOTH SIDES PER IPC-SM-840, TYPE A, CLASS B. COLOR-GREEN. THERE SHALL BE NO SOLDERMASK ON ANY LAND.
7. SILKSCREEN THE LEGEND ON BOTH SIDES USING NON CONDUCTIVE EPOXY INK, COLOR-WHITE. THERE SHALL BE NO INK ON ANY LAND.
8. THE .006 TRACES (LAYER 1 & 4) TO BE 50 OHM SINGLE ENDED AND THE .005/.010 TRACES/GAP (LAYER 1 & 4) TO BE 100 OHM DIFFERENTIAL IMPEDANCE. AND THE .0055/.0075 TRACES/GAP (LAYER 1) TO BE 90 OHM DIFFERENTIAL IMPEDANCE. THE DIELECTRIC REFERENCED IN BOARD STACK DETAIL IS SUGGESTED. HOWEVER, TRACE WIDTHS AND OR DIELECTRIC THICKNESS MAY BE MICRO-MODIFIED IN ORDER TO FABRICATE BOARDS TO THE REQUIRED IMPEDANCE NOMINALS TO A TOLERANCE OF +/- 5%.